

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Clam 1-9 (canceled)

Claim 10 (previously presented) A method eliminating moisture from electronic components, the method comprising:

- storing electronic components in a storage area;
- maintaining a warm and dry atmosphere in the storage area by enclosing the storage area and injecting a warm and dry gas into the storage area at a flow rate and temperature which are controlled to eliminate moisture from the components in the storage area; and
- removing about 0.1% or more of the weight of the components by elimination of moisture while the components are stored in the storage area.

Claim 11 (original) The method of Claim 10, wherein the component storage area is a feeder cart for storing the components.

Claim 12 (original) The method of Claim 10, wherein the component storage area is a cabinet receiving at least one feeder cart for storing the components.

Claim 13 (original) The method of Claim 10, wherein the component storage area is a storage cabinet for storing the components.

Claim 14 (original) The method of Claim 10, wherein the temperature control system controls the temperature of the dry gas to about 10°C to about 60°C.

Claim 15 (original) The method of Claim 10, wherein the temperature control system controls the temperature of the dry gas to about 20°C to about 50°C.

Claim 16 (original) The method of Claim 10, wherein a flow rate of the dry gas delivered to the storage area is controlled by a control system including a humidity sensor within the component storage area.

Claim 17 (cancelled)